

Data Sheet Issue:- 2

Phase Control Thyristor Types N5946F#180 to N5946F#220

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V _{DRM}	Repetitive peak off-state voltage, (note 1)	1800-2200	V
V _{DSM}	Non-repetitive peak off-state voltage, (note 1)	1800-2200	V
V _{RRM}	Repetitive peak reverse voltage, (note 1)	1800-2200	V
V _{RSM}	Non-repetitive peak reverse voltage, (note 1)	1900-2300	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS	
I _{T(AV)}	Mean on-state current. T _{sink} =55°C, (note 2)	urrent. T _{sink} =55°C, (note 2)		А
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 2)		4073	A
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 3)		2459	А
I _{T(RMS)}	Nominal RMS on-state current. T _{sink} =25°C, (note 2)		11748	А
I _{T(d.c.)}	D.C. on-state current. T _{sink} =25°C, (note 4)		10155	А
I _{TSM}	Peak non-repetitive surge current t_p =10ms, V_{RM} =60	72	kA	
I _{TSM2}	Peak non-repetitive surge current $t_p=10ms$, $V_{RM} \le 10$	80	kA	
l ² t	$I^{2}t$ capacity for fusing t _p =10ms, V _{RM} =60%V _{RRM} , (not	25.9×10 ⁶	A ² s	
l ² t	$I^{2}t$ capacity for fusing t_{p} =10ms, V_{RM} ≤10V, (note 5)		32.0×10 ⁶	A ² s
		continuous, 50Hz	75	
(di/dt) _{cr}	Maximum rate of rise of on-state current, (Note 6)	repetitive, 50Hz, 60s	150	A/µs
		non-repetitive	300	
V _{RGM}	Peak reverse gate voltage		5	V
P _{G(AV)}	Mean forward gate power	5	W	
P _{GM}	Peak forward gate power	30	W	
T _{HS}	Operating temperature range		-40 to +125	°C
T _{stg}	Storage temperature range		-40 to +150	°C

Notes: -

- 1) De-rating factor of 0.13% per °C is applicable for T_i below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125°C T_i initial.
- 6) V_D=67% V_{DRM}, I_{TM}=1500A, I_{FG}=2A, t_r≤0.5µs, T_{case}=125°C.

Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
V _{TM}	Maximum peak on-state voltage	-	-	1.25	I _{TM} =6000A	V
V _{T0}	Threshold voltage	-	-	0.855		V
r _T	Slope resistance	-	-	0.065		mΩ
(dv/dt) _{cr}	Critical rate of rise of off-state voltage	1000	-	-	V_{D} =80% V_{DRM}	V/µs
I _{DRM}	Peak off-state current	-	-	200	Rated V _{DRM}	mA
I _{RRM}	Peak reverse current	-	-	200	Rated V _{RRM}	mA
V _{GT}	Gate trigger voltage	-	-	3.0		V
I _{GT}	Gate trigger current	-	-	300	T _j =25°C, V _D =10V, I _T =2A	mA
V _{GD}	Gate non-trigger voltage	-	-	0.25	Rated V _{DRM}	V
I _H	Holding current	-	-	1000	T _j =25°C	mA
t _{gd}	Gate controlled turn-on delay time	-	0.4	2.0	I _{FG} =2A, t _r =0.5μs, V _D =67%V _{DRM} ,	μs
t _{gt}	Turn-on time	-	0.9	3.0	I_{TM} =2000A, di/dt=10A/µs, T _j =25°C	
Q _{rr}	Recovered Charge	-	5800	-		μC
Q _{ra}	Recovered Charge, 50% chord	-	3700	5300	1 40000 t 2mp di/dt 50/4p)/ 50//	μC
l _{rm}	Reverse recovery current	-	140	-	I_{TM} =4000A, t _p =2ms, di/dt=5A/µs, V _r =50V	А
t _{rr}	Reverse recovery time, 50% chord	-	55	-		μs
+	Turn-off time	-	300	-	I _{TM} =4000A, t _p =2ms, di/dt=5A/μs, V _r =50V, V _{dr} =67%V _{DRM} , dV _{dr} /dt=20V/μs	
t _q		-	500	-	I _{TM} =4000A, t _p =2ms, di/dt=5A/µs, V _r =50V, V _{dr} =67%V _{DRM} , dV _{dr} /dt=200V/µs	μs
D	Thermel registered, junction to besteink	-	-	0.0065	Double side cooled	K/W
R _{thJK}	Thermal resistance, junction to heatsink	-	-	0.0130	Single side cooled	K/W
F	Mounting force	81	-	99	Note 2	kN
W _t	Weight	-	2.8	-		kg

Notes: -

1) Unless otherwise indicated $T_j=125$ °C.

2) For other clamp forces, please consult factory

Notes on rupture rated packages. This product is available with a non-rupture rated package. For additional details on these products, please consult factory.

Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	V _{DRM} V _{DSM} V _{RRM} V	V _{RSM} V	V _D V _R DC V
18	1800	1900	1150
20	2000	2100	1250
22	2200	2300	1350

2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

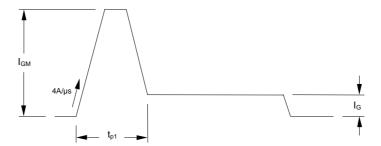
A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_i below 25°C.

4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

5.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20µs or sufficient to allow the anode current to reach ten times I_L , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_G should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 1000A/µs at any time during turn-on on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 500A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Square wave frequency ratings

These ratings are given for load component rate of rise of on-state current of 50A/µs.

 $W_{AV} = \frac{\Delta T}{R_{th}}$ $\Delta T = T_{j \max} - T_{K}$

8.0 Computer Modelling Parameters

8.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^{2} + 4 \cdot ff^{2} \cdot r_{T} \cdot W_{AV}}}{2 \cdot ff^{2} \cdot r_{T}}$$

Where V_{T0} =0.855, r_T=0.065 Ω ,

 R_{th} = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave Double Side Cooled	0.00717	0.00707	0.00698	0.00689	0.00673	0.00652	0.0065
Square wave Single Side Cooled	0.0137	0.01359	0.01349	0.0134	0.01323	0.01301	0.0130
Sine wave Double Side Cooled	0.00709	0.00697	0.00687	0.00678	0.00654		
Sine wave Single Side Cooled	0.0136	0.01348	0.01337	0.01328	0.01303		

and:

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.464	2.449	2	1.732	1.414	1.149	1
Sine wave	3.98	2.778	2.22	1.879	1.57		

8.2 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}} \right)$$

Where p = 1 to *n*, *n* is the number of terms in the series and:

- t = Duration of heating pulse in seconds.
- r_{t} = Thermal resistance at time t.
- r_p = Amplitude of p_{th} term.
- τ_p = Time Constant of r_{th} term.

The coefficients for this device are shown in the tables below:

	D.C. Double Side Cooled						
Term	1	2	4	5			
r _p	3.424745×10 ⁻³	1.745273×10 ⁻³	8.532017×10 ⁻⁴	3.457329×10 ⁻⁴			
$ au_{ m p}$	1.125391	0.1878348	0.02788979	8.430889×10 ⁻³			

D.C. Single Side Cooled						
Term	1	2	5	6		
r _p	8.375269×10 ⁻³	2.518437×10 ⁻³	1.193758×10 ⁻³	7.45432×10 ⁻⁴		
$ au_{ m p}$	8.929845	0.4711304	0.08221244	0.01221961		

8.3 Calculating V_T using ABCD Coefficients

The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways;

- (i) the well established V_{T0} and r_T tangent used for rating purposes and
- (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for the hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

25°C Coefficients			125°C Coefficients
А	0.945893757	А	0.572724113
В	-0.01897598	В	0.01470079
С	1.45867×10 ⁻⁵	С	2.391723×10 ⁻⁵
D	4.798213×10 ⁻³	D	5.239924×10 ⁻³

9.0 Snubber Components

When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

10.0 Reverse recovery ratings

- (i) Q_{ra} is based on 50% I_{rm} chord as shown in Fig. 1
- (ii) Q_{rr} is based on a 150µs integration time i.e.

$$Q_{rr} = \int_{0}^{150\,\mu s} i_{rr}.dt$$

(iii)
$$K Factor = \frac{t_1}{t_2}$$

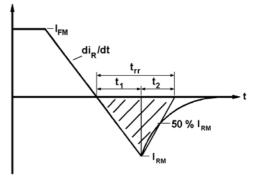
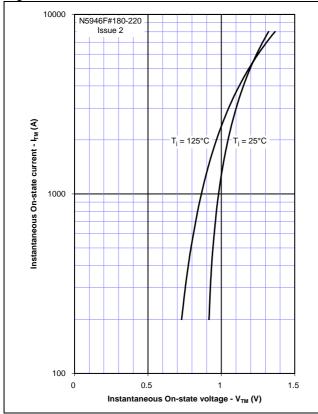


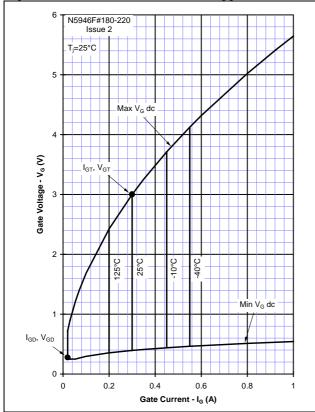
Fig. 1

<u>Curves</u>

Figure 1 – On-state characteristics of Limit device







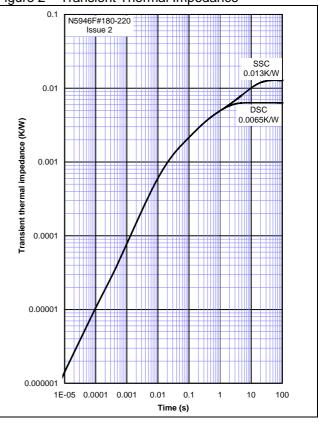
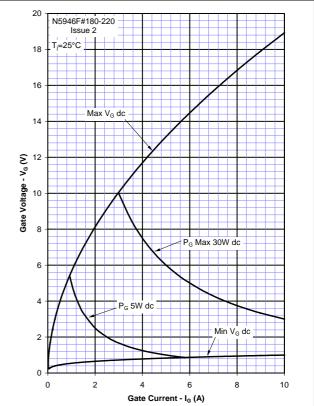
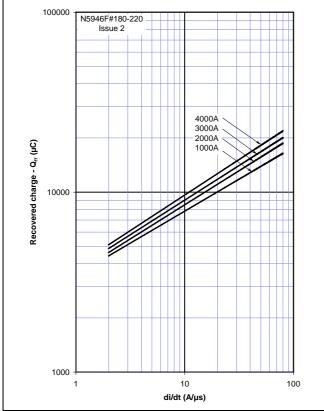


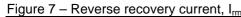
Figure 2 – Transient Thermal Impedance

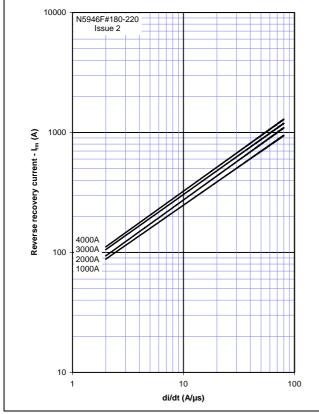
Figure 4 – Gate Characteristics – Power Curves

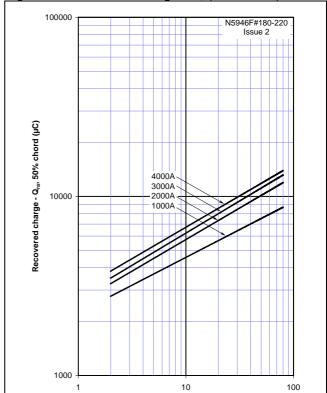








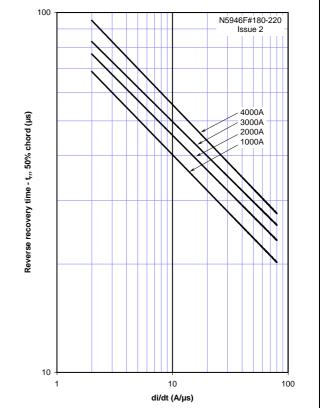




di/dt (A/µs)

Figure 6 – Recovered charge, Q_{ra} (50% chord)

Figure 8 - Reverse recovery time, t_{rr}



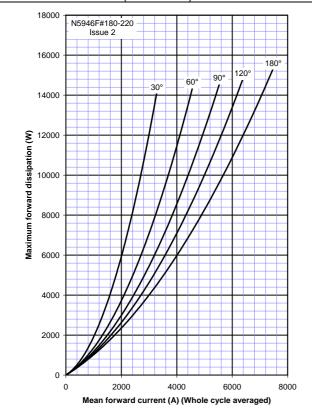


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

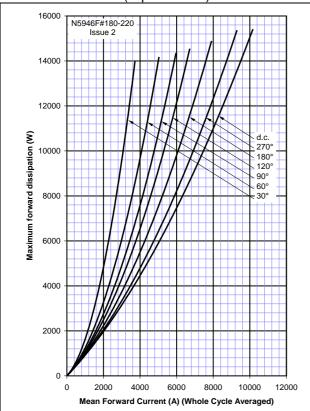


Figure 10 – On-state current vs. Heatsink temperature – Double Side Cooled (Sine wave)

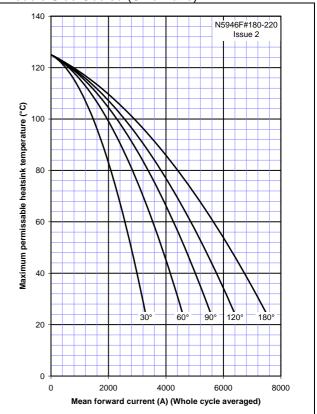
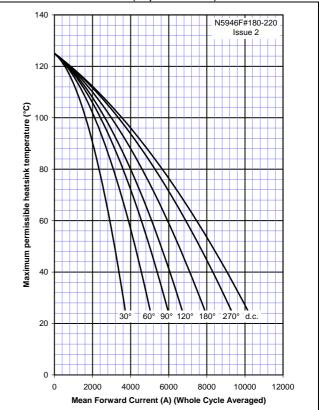


Figure 12 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)



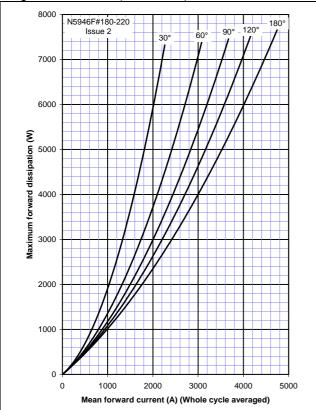
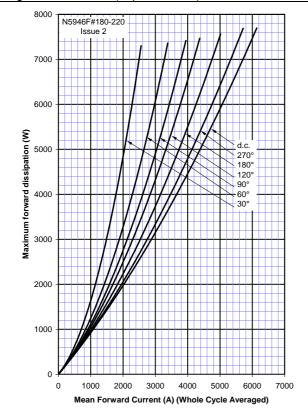
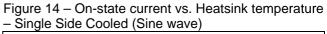


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

Figure 15 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)





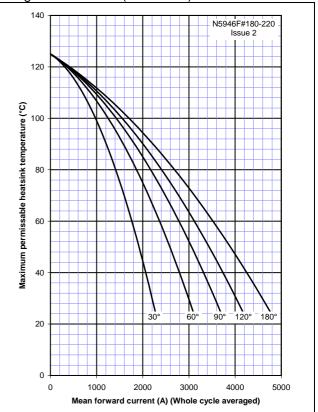
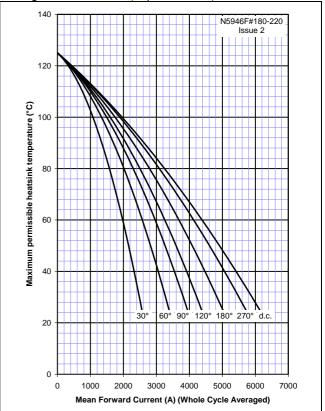


Figure 16 – On-state current vs. Heatsink temperature – Single Side Cooled (Square wave)



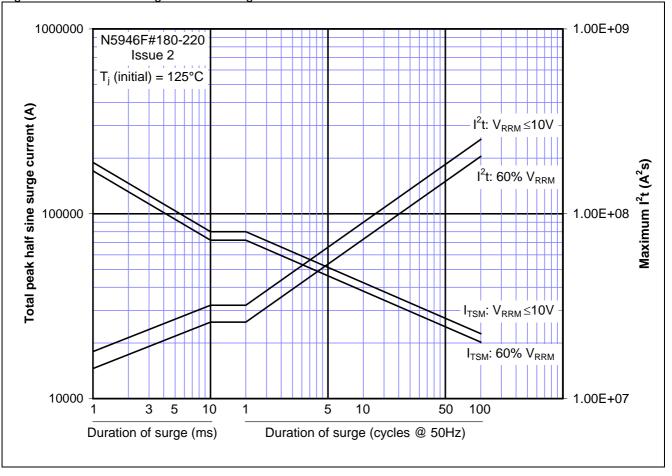


Figure 17 – Maximum surge and I²t Ratings

Outline Drawing & Ordering Information

